

REMARKS AND ARGUMENTS

Claim Rejections - 35 USC § 102

The Examiner has rejected claims 13-19, 33-34 and 36-37 under 35 U.S.C. 102(b) as being anticipated by US 6329224 to Nguyen (hereafter "Nguyen"). Applicants respectfully disagree with the Examiner's analysis of the prior art, specifically the Nguyen reference. However, Applicants have amended claims 13 and 33 to more fully describe the subject matter therein and to expedite allowance of the claims.

Specifically, the Examiner states that Nguyen teaches all of the limitations of Applicants' claims 13 and 33. The method of claim 13, as amended, requires "removing said cured or treated coating material with said embedded semiconductor devices from said formation cavity." Support can be found for this amendment in the specification as originally filed. (See Specification: page 10, line 28 - page 11, line 1). The method of claim 13 teaches introducing a coating material and curing the material while the devices are still inside the formation cavity.

Nguyen teaches a method of encapsulating a plurality of microelectronic assemblies using disposable frames. (See Nguyen: Abstract). However, Nguyen teaches a different process wherein the devices are mounted to a flexible tape within an encapsulation fixture and, unlike the method of claim 13, are removed from the encapsulation fixture prior to curing the devices. (See Nguyen: column 10, lines 15-55). Therefore, Nguyen does not teach a process whereby "cured or treated...semiconductor devices [are removed] from the cavity." Furthermore, Nguyen describes including the tape (which the

Examiner states is analogous to Applicants' upper and lower sections of the formation cavity) as a part of the finished semiconductor device, such as a heat spreader or a lens. This description illustrates that the devices are, in fact, never removed from the tape; whereas Applicants' claim 13 expressly requires that the devices are removed from the formation cavity.

Because Nguyen does not teach, suggest or disclose all of the limitations of Applicants' claim 13, the claim is not anticipated. Claim 13 is otherwise allowable.

Claim 33 contains a similar amendment as the amendment in claim 13, and for at least the same reasons discussed above, claim 33 is allowable over the prior art.

Claims 14 and 34 have been canceled.

Claims 15-19 depend from allowable claim 1 and, as such, are also allowable.

Claims 36 and 37 depend from allowable claim 33 and, as such are also allowable.

For at least the reasons stated above, Applicants respectfully request the withdrawal of the rejections of claims 13, 15-19, 33, 36 and 37.

Claim Rejections - 35 USC § 103

The Examiner has rejected claim 35 under 35 U.S.C. 103(a) as being unpatentable over Nguyen in view of US 6252254 to Soules et al. (hereafter "Soules"). Applicants respectfully disagree with the Examiner's analysis of the prior art.

Claim 35 depends from allowable claim 33 and, as such, is also allowable. For at least the reasons stated above, Applicants respectfully request that the rejection of claim 35 be withdrawn.

New Claims

New claim 38 has been added. The claim discloses a method for coating a plurality of semiconductor devices. The claim requires that the coating material is cured around the semiconductor devices, forming a "sheet of semiconductor devices and coating material" inside the formation cavity. The entire sheet is removed from the upper and lower sections of the frame that define the formation cavity. The sheet is then separated into individual coated semiconductor devices. Applicants submit that the new claim is fully supported by the application as originally filed and is allowable.

CONCLUSION

Applicant submits that claims 13, 15-19, 33, and 35-38 are in condition for allowance, and applicant respectfully requests that a timely Notice of Allowance be issued in this case.

Respectfully submitted,



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June 28, 2006

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